

QFS-078-04.25-L-D-PC4

QFS-052-04.25-L-D-RF1

QFS-PC, QFS-RF SERIES

(0.635 mm) .025"

HIGH-SPEED COMBO RF & POWER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QFS

Insulator Material:

Liquid Crystal Polymer
Contact & Ground

Plane Material:

Phosphor Bronze

Plating:

Au over 50 μ" (1.27 μm) Ni
(Tin on Ground Plane Tail)

Current Rating:

Signal Contact:

2.6 A per pin

(2 pins powered)

Power Contact:

4.0 A per pin

(4 pins powered per end)

Ground Plane:

15.7 A per ground plane

(1 ground plane powered)

Voltage Rating:

300 VAC mated with QMS

Operating Temp:

-55 °C to +125 °C

RoHS Compliant:

Yes

Board Mates:

QMS-PC, QMS-RA-PC,

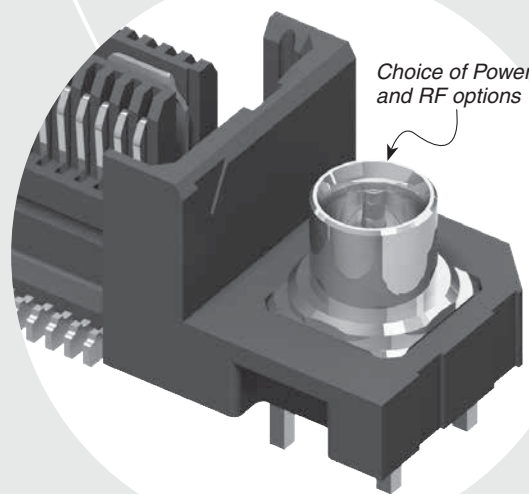
QMS-RF

Standoffs:

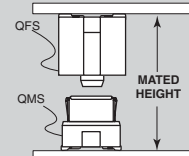
SO

RUGGEDIZED
BY SAMTEC

- Increased insertion depth
- Integral guide post



APPLICATION



QMS LEAD STYLE	MATED HEIGHT*
-05.75	(10.00) .394
-06.75	(11.00) .433

*Processing conditions will affect mated height. See SO Series for board space tolerances.

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (026-078)

Board Stacking:

For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see

www.samtec.com/quality



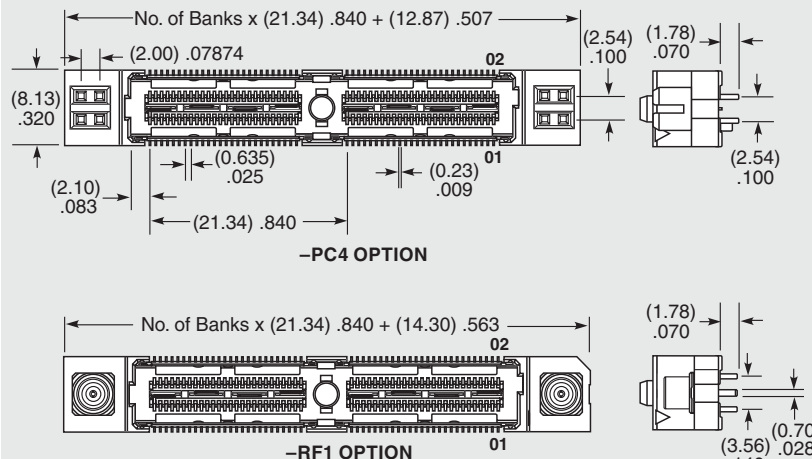
FILE NO. E111594

ALSO AVAILABLE (MOQ Required)

- Other platings
- Differential Pairs
- Retention Pins
- 8 Power Pins/End for (1.60 mm) .062" thick board
- 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- 2 RF Connectors/End
- Hot Pluggable

Note:
Some lengths, styles and options are non-standard, non-returnable.

QFS	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	D	END OPTION
	-026, -052, -078 (52 total pins per bank)	-04.25 = 04.25 mm	-L = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)		-PC4 = 4 Power Pins per End for (1.60 mm) .062" thick Board (N/A with -RF1) -RF1 = One RF Jack per End (N/A with -PC4)



OTHER SOLUTIONS



See SO Series for precision machined standoffs.

Due to technical progress, all designs, specifications and components are subject to change without notice.